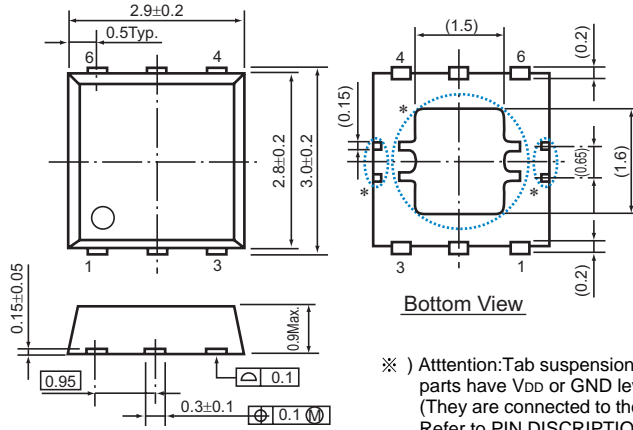


• HSON-6

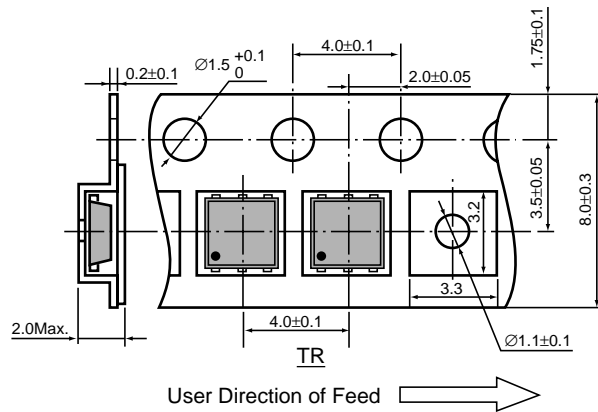
Unit: mm

PACKAGE DIMENSIONS



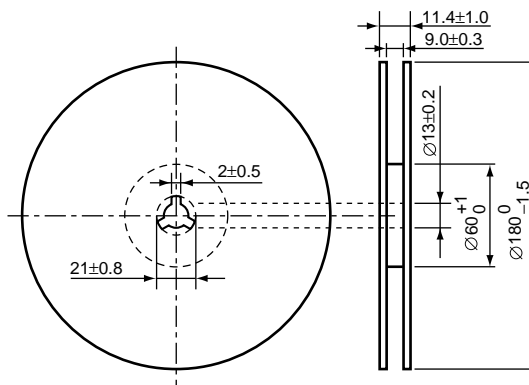
※) Attention: Tab suspension leads in the circle parts have VDD or GND level. (They are connected to the back side of this IC.) Refer to PIN DISCRPTION. Do not connect to other wires or land patterns.

TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=3000pcs)



POWER DISSIPATION (HSON-6)

This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

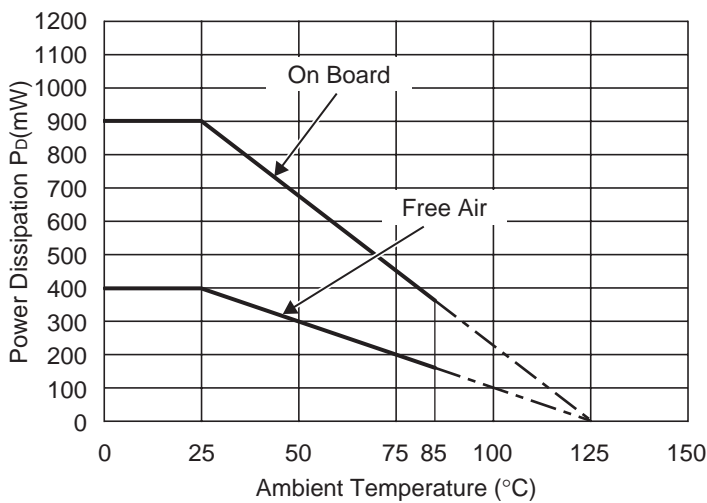
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plactic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

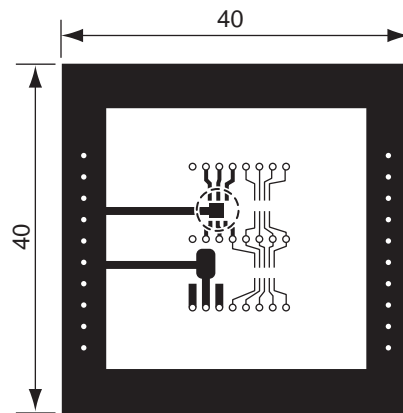
Measurement Result

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	Standard Land Pattern	Free Air
Power Dissipation	900mW	400mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/0.9W=111^{\circ}C/W$	250°C/W
		$\theta_{jc}=43.5^{\circ}C/W$



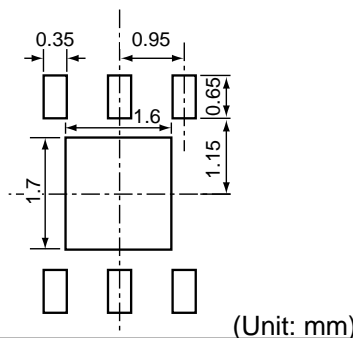
Power Dissipation



Measurement Board Pattern

○ IC Mount Area Unit : mm

RECOMMENDED LAND PATTERN



(Unit: mm)